



SimpoleD SimpoleD-58 Series Star Heat Sinks Ø58mm for COB Modular Product Brief

Features VS Benefits

- * Mechanical compatibility with direct mounting of the LED modules to the LED cooler and thermal performance matching the lumen packages.
 - * Thermal resistance range $R_{th}(3.85^{\circ}\text{C/W}; 4.55^{\circ}\text{C/W})$.
 - * Modular design with mounting holes foreseen for direct mounting of a wide range of LED modules and COB's:
 - * Diameter 58mm - Standard height 50.0mm / 70.0mm , Other heights on request.
 - * Extruded from highly conductive aluminum.
- 2 standard colors - clear anodised - black anodised
- Zhaga Book 3 Spot Light Modules Edison ,Bridgelux , Osram ,Citizen ,Lumileds ,Cree ,
Tridonic , Vossloh-Schwabe ,Seoul ,LG ,Lustrous ,Prolight ,Samung ,SHARP , Luminus



- 01) Bridgelux ESS, ESR, Vero 10;
- 02) Citizen CLL022-CLU024, CLL032-CLU034;
- 03) Cree XLamp CXA13xx, CXA15xx, CSA18xx;
- 04) Lumileds Luxeon COB's 1203, 1204, 1205, Luxeon K arrays K12, K16;
- 05) Osram PrevaLED Core, SOLERIQ P and SOLERIQ S LED engines.
- 06) Seoul Semiconductor ZC6, ZC12, ZC18, ZC25;
- 07) Tridonic TALEXX module SLE modules;
- 08) LG Innotek LEMWM18 10W, 13W, 17W
- 09) Edison EdiLex SLM and EdiLex II COB LED engines.
- 10) Lustrous LUSTRON 6 series LL604F, LL608D, LL613F, LL620F
- 11) Prolight Opto PABS, PABA, PACB, PANA
- 12) Samung LC013, LC019, LC026 COB LED engines.
- 13) SHARP Mini Zenigata Intermo and Mega Zenigata LED engines.
- 14) Vossloh-Schwabe LUGA Shop LED engines.
- 15) Luminus C##9, C##14 LED engines.

Order Information

Example: SimpoleD-5870-B-#

Example: SimpoleD-58 **1** - **2** - **3**

1 Hight (mm)

2 Anodising Color

B-Black

C-Clear

Z-Custom

3 Mounting Options - see graphics for details Combinations available

Ex.order code - 12

means option 1 and 2 combined

MingFa recommends the use of a high thermal conductive interface between the LED module and the LED cooler. Either thermal grease, a thermal pad or a phase change thermal pad thickness 0.1-0.15mm is recommended.

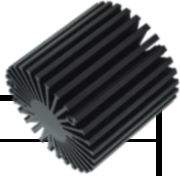
Notes:

- Mentioned models are an extraction of full product range.
- For specific mechanical adaptations please contact MingfaTech.
- MingfaTech reserves the right to change products or specifications without prior notice.



SimpoleD SimpoleD-58 Series Star Heat Sinks $\Phi 58\text{mm}$ for COB Modular Product Brief

The product data table



Brand	Mingfa Tech	
Series Name	SimpoleD star heat sinks	
Series Number	SimpoleD-58	
Manufacturing Technology	Aluminum extrusion	
Material	AL6063-T5	
Color & Finishing	Black Anodized	
Certification	CE, ROHS, WEEE	
Diameter(mm)	$\Phi 58$	
Height(mm)	50.0mm	70.0mm
Item Number	SimpoleD-5850	SimpoleD-5870
Max. Lumen	1600 lm	1900 lm
Dissipated Power (Ths-amb,50°C)	11.0 W	13.0 W
Thermal Resistance Rth (°C/W)	4.55°C/W	3.85 °C/W
Cooling Surface Area (mm²)	36868.0 mm²	58826.0 mm²
Net Weight (g)	174.0 g	244.0 g
Quantity (pcs/CTN)	64 pcs	48 pcs
Modular Types	COB	COB
For Environments	Indoor area	
For Lightings	Down lights,Architectural lights	
For Application	Retail & Hospitality,Mall & Food,Architectural & Museums,Office & Education, Station & Airport,Healthcare	
For LED brands	Adura,Bridgelux,BJB,Citizen,Cree,Edison,GE,LG,Lumileds,Lumens,Luminus,Ledil,Nichia, Osram,Prolight Opto,Samsung,Seoul,Sharp,Tridonic,Vossloh Schwabe,Zhaga	

* 3D files are available in ParaSolid, STP and IGS on request

* The thermal resistance Rth is determined with a calibrated heat source of 14mm×14mm central placed on the heat sink, Tamb 40° and an open environment. Reference data @ heat sink to ambient temperature rise Ths-amb 50°C
The thermal resistance of a LED cooler is not a fix value and will vary with the applied dissipated power Pd

* Dissipated power Pd. Reference data @ heat sink to ambient temperature rise Ths-amb 50°C
The maximal dissipated power needs to be verified in function of required case temperature Tc or junction temperature Tj and related to the estimated ambient temperature where the light fixture will be placed
Please be aware the dissipated power Pd is not the same as the electrical power Pe of a LED module

To calculate the dissipated power please use the following formula: $P_d = P_e \times (1 - \eta_L)$

Pd - Dissipated power

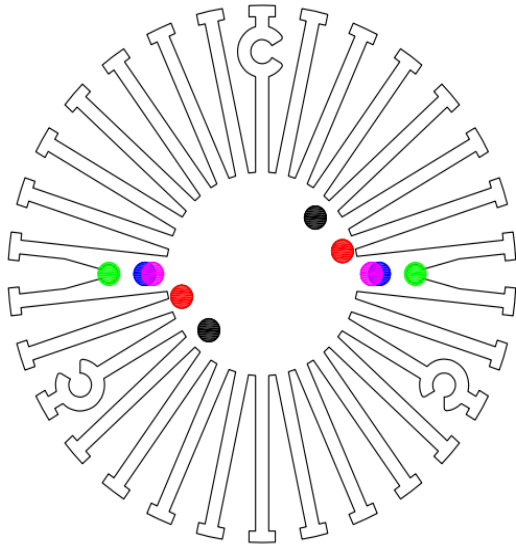
Pe - Electrical power

η_L = Light efficiency of the LED module

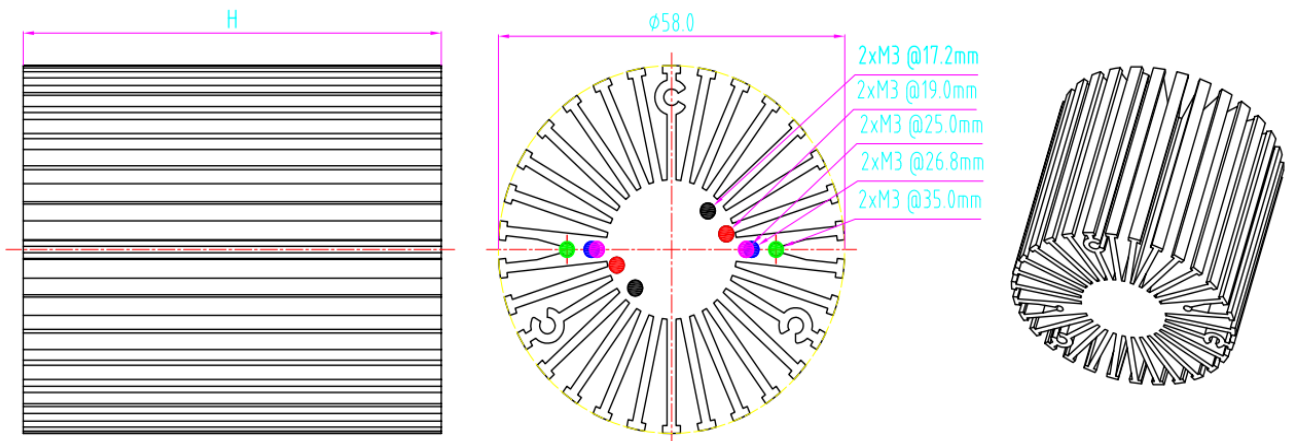


SimpoLED SimpoLED-58 Series $\Phi 58\text{mm}$ COB Heat Sink Drawings

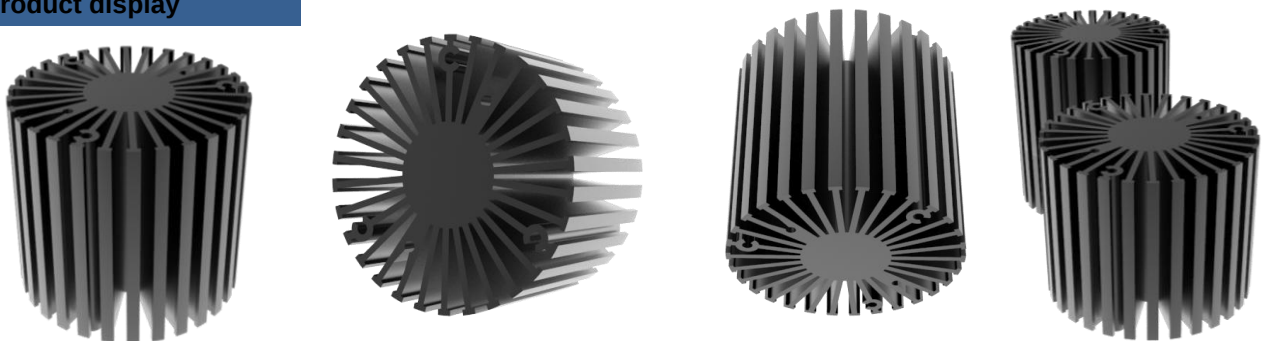
Drawings & Type Selection



MOUNTING OPTION		THREAD HOLE DISTANCE
A1	●	17.2 mm @ 2-180°
A2	●	19.0 mm @ 2-180°
A3	●	25.0 mm @ 2-180°
A4	●	26.8 mm @ 2-180°
A5	●	35.0 mm @ 2-180°



Product display



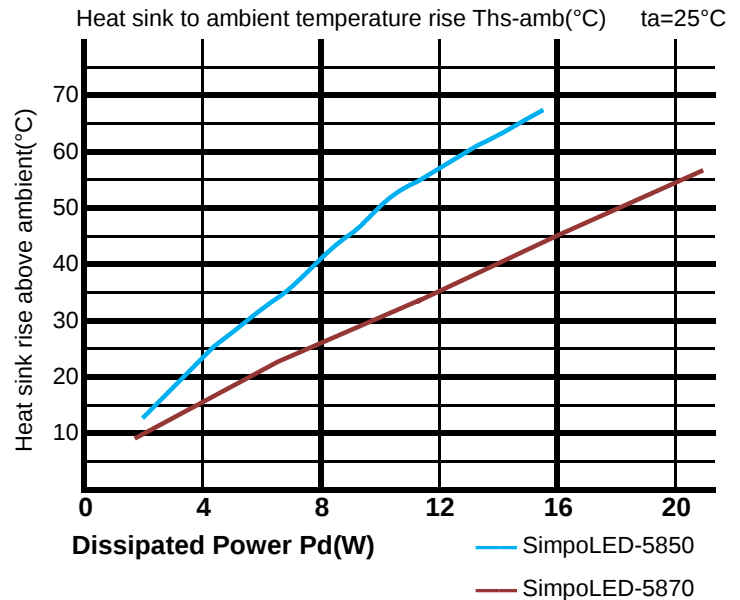


SimpoleD SimpoLED-58 Series $\Phi 58\text{mm}$ Material AL6063-T5 COB Star Heat Sinks Thermal Data

The thermal data table

SimpoLED-58 thermal data

Dissipated Power Pd(W)	Pd = Pe x (1- η L)	Heat sink to ambient temperature rise Ths-amb (°C)	Heat sink to ambient temperature rise Ths-amb (°C)
		SimpoLED-5850	SimpoLED-5870
2		14.5	10.0
4		25.0	16.0
6		34.5	22.0
8		43.0	28.0
10		51.0	32.5
12		58.0	37.5
20			55.3



* Please be aware the dissipated power Pd is not the same as the electrical power Pe of a LED module.

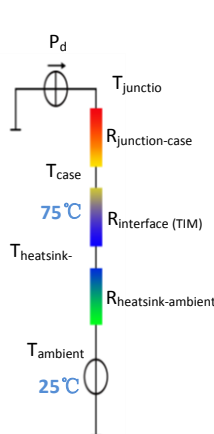
*To calculate the dissipated power please use the following formula: $P_d = P_e \times (1 - \eta_L)$.

Pd - Dissipated power ; Pe - Electrical power ; η_L = Light efficiency of the LED module;

*The aluminum substrate side of the package outer shell is thermally connected to the heat sink via TIM (Thermal interface material).

MingFa recommends the use of a high thermal conductive interface between the LED module and the LED cooler.

Either thermal grease, A thermal pad or a phase change thermal pad thickness 0.1-0.15mm is recommended.



*Thermal resistance is a heat property and a measurement of a temperature difference by which an object or material resists a heat flow.

Geometric shapes are different, the thermal resistance is different. Formula: $\theta = (T_{hs} - T_a) / P_d$

θ - Thermal Resistance [$^\circ\text{C}/\text{W}$]; T_{hs} - Heatsink temperature ; T_a - Ambient temperature ;

*The thermal resistance between the junction section of the light-emitting diode and the aluminum substrate side of the package outer

shell is $R_{\text{junction-case}}$, the thermal resistance of the TIM outside the package is $R_{\text{interface (TIM)}}$ [$^\circ\text{C}/\text{W}$], the thermal resistance with the heat sink is $R_{\text{heatsink-ambient}}$ [$^\circ\text{C}/\text{W}$], and the ambient temperature is T_{ambient} [$^\circ\text{C}$].

*Thermal resistances outside the package $R_{\text{interface (TIM)}}$ and $R_{\text{heatsink-ambient}}$ can be integrated

into the thermal resistance $R_{\text{case-ambient}}$ at this point. Thus, the following formula is also used:

$$T_{\text{junction}} = (R_{\text{junction-case}} + R_{\text{case-ambient}}) \cdot P_d + T_{\text{ambient}}$$